

Pin Descriptions

Pin Name	Description				
Α	Data Input				
В	Data Input				
GND	Ground				
Y	Data Output				
Vcc	Supply Voltage				

Logic Diagram



Function Table

Inp	Output	
Α	В	Y
Н	Х	Н
Χ	Н	Н
L	L	L



Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{ok}	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 4)

Symbol		Parameter	Min	Max	Unit	
\/	On a ratio a Valta as	Operating	1.4	5.5	V	
V_{CC}	Operating Voltage	Data retention only	1.2		V	
		V _{CC} = 1.4 V to 1.95 V	0.65 X V _{CC}			
\/	High lavel lagest Valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
V_{IH}	High-level Input Voltage	V _{CC} = 3 V to 3.6 V	2		V	
		V _{CC} = 4.5 V to 5.5 V	0.7 X V _{CC}			
		V _{CC} = 1.4 V to 1.95 V		0.35 X V _{CC}		
W	L our lovel input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V	
		V _{CC} = 4.5 V to 5.5 V		0.3 X V _{CC}		
Vı	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	V _{CC}	V	
		Vcc=1.4 V		-3		
		V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-8		
I _{OH}	High-level output current	V 2V		-16	mA	
		$V_{CC} = 3 V$		-24		
		V _{CC} = 4.5 V		-32		
		Vcc=1.4 V		3		
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		8	mΑ	
I _{OL}	Low-level output current			16		
		$V_{CC} = 3 V$		24		
		V _{CC} = 4.5 V		32		
		V _{CC} = 1.4 to 3V		20		
Δt/ΔV	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5		
T _A	Operating free-air temperature		-40	85	°C	

Note: 4. Unused inputs should be held at Vcc or Ground.



Electrical Characteristics (All typical values are at Vcc = 3.3V, T_A = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit	
		$I_{OH} = -100 \mu A$	1.4 V to 5.5V	V _{CC} - 0.1				
		$I_{OH} = -3mA$	1.4 V	1.05				
	LEST LA STORY	$I_{OH} = -4mA$	1.65 V	1.2				
V_{OH}	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V	
	Voltage	I _{OH} = -16mA	3 V	2.4				
		$I_{OH} = -24mA$	3 V	2.3				
		$I_{OH} = -32mA$	4.5 V	3.8				
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1		
		$I_{OL} = 3mA$	1.4 V			.4		
		$I_{OL} = 4mA$	1.65 V			0.45		
V _{OL} High	High-level Input Voltage	$I_{OL} = 8mA$	2.3V			0.3	V	
		$I_{OL} = 16mA$	3 V			0.4		
		$I_{OL} = 24mA$	3 V			0.55		
		$I_{OL} = 32mA$	4.5			0.55		
l _l	Input Current	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μΑ	
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 5.5V$	0			± 10	μΑ	
I _{cc}	Supply Current	$V_1 = 5.5V$ of GND $I_0=0$	1.4 V to 5.5V			10	μΑ	
ΔI_{CC}	Additional Supply Current	One input at V _{CC} – 0.6 V Other inputs at V _{CC} or GND	3 V to 5.5V			500	μA	
Ci	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	3.3		3.5		pF	
		SOT25	(Note 5)		204			
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT353	(Note 5)		371		°C/W	
	Junction-to-Ambient	DFN1410	(Note 5)		430			
		SOT25	(Note 5)		52			
θ_{JC}	Thermal Resistance	SOT353	(Note 5)		143		°C/W	
	Junction-to-Case	DFN1410	(Note 5)		190			
		1						

Note: 5. Test condition for SOT25, SOT353, and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		3.3 V 3.3 V	Vcc :	= 5 V).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	1.9	7.2	1.3	5	0.6	3.5	0.7	2.9	0.7	2.9	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		3.3 V 3.3 V	Vcc :	= 5 V).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A or B	Y	2.8	8	1.9	5.6	0.9	4.4	0.9	3.6	0.9	3.6	ns

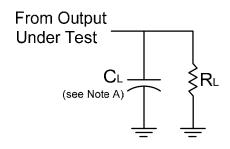
Operating Characteristics

 $T_A = 25$ °C

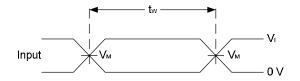
P	arameter	Test Conditions	Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V TYP	Vcc = 3.3 V	Vcc = 5 V	Unit
$C_{\sf pd}$	Power dissipation capacitance	f = 10 MHz	20	20	20	21	22	pF



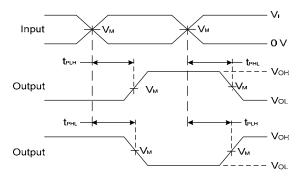
Parameter Measurement Information



Vcc	In	puts	V	C.	D.
VCC	Vı	t _r /t _f	V _M	CL	R_L
1.5V±0.1V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
1.8V±0.15V	V _{cc}	≤2ns	V _{CC} /2	15pF	1ΜΩ
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	15pF	1ΜΩ



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

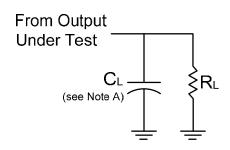
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

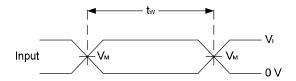
Figure 1. Load Circuit and Voltage Waveforms



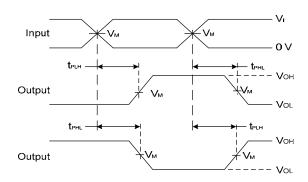
Parameter Measurement Information (Continued)



Vcc	Inp	outs	V _M	CL	R_L
	VI	t _r /t _f	- 101	o _L	
1.5V±0.1V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ
1.8V±0.15V	V _{cc}	≤2ns	V _{CC} /2	30pF	1ΚΩ
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.

C. Inputs are measured separately one transition per measurement.

D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

Figure 2. Load Circuit and Voltage Waveforms



Ordering Information

 74LVCE1G 32 XXX - 7

 Logic Device
 Function
 Package
 Packing

 74: Logic Prefix
 32: 2-Input
 W5: SOT25
 7: Tape & Reel

 VCE: 1.4 to 5.5V
 OR-Gate
 SE: SOT353

FZ4: DFN1410

LVCE: 1.4 to 5.5V Family

1G : One gate

	Device	Package Packaging		7" Tape and Reel			
	Device	Code	(Note 5)	Quantity	Part Number Suffix		
Pb ,	74LVCE1G32W5-7	W6	SOT25	3000/Tape & Reel	-7		
Pb ,	74LVCE1G32SE-7	SE	SOT353	3000/Tape & Reel	-7		
Pb ,	74LVCE1G32FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7		

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Marking Information

(1) SOT25 and SOT353

(Top View)

5 XX Y W X

2

1

XX: Identification code

Y: Year 0~9

<u>W</u>: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents 52 and 53 week

X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G32W5	SOT25	PW
74LVCE1G32SE	SOT353	PW

(2) DFN1410

(Top View)

3

<u>XX</u> $\underline{Y}\underline{W}\underline{X}$ XX: Identification Code

<u>Y</u> : Year : 0~9

 $\overline{\underline{W}}$: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

52 and 53 week

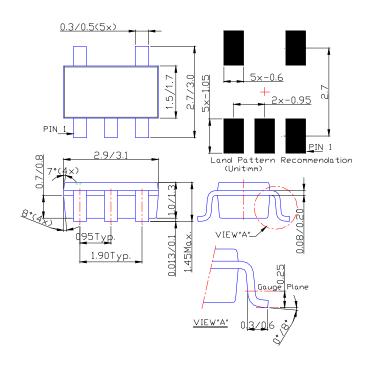
X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G32FZ4	DFN1410	PW

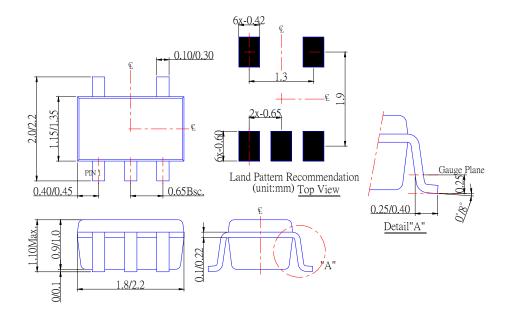


Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



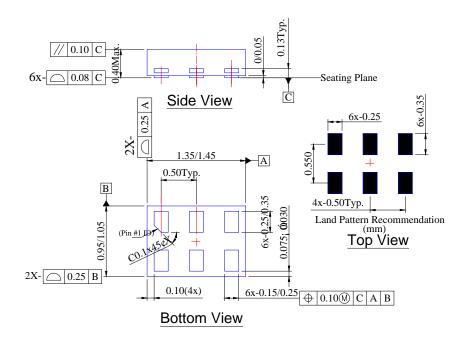
(2) Package Type: SOT353





Package Outline Dimensions (All Dimensions in mm)

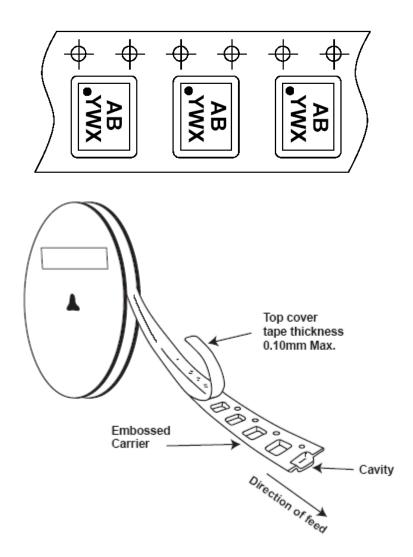
(3) Package Type: DFN1410





Taping Orientation (Note 7)

For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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